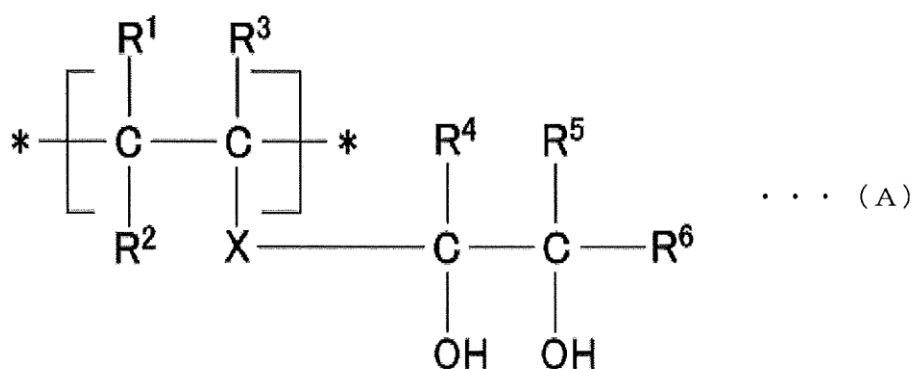


POLISHING COMPOSITION AND METHOD OF POLISHING SILICON WAFER

ABSTRACT

A polishing composition is provided that can reduce minute defects and haze on the semiconductor wafer after polishing and is highly capable of hydophilizing the semiconductor wafer. A polishing composition includes: an abrasive; a basic compound; and a water-soluble polymer, the water-soluble polymer being a copolymer with a vinyl alcohol-based resin having a 1,2-diol structural unit represented by the following general formula, (A), polymerized with vinylpyrrolidone:

[Chem. 1]



Here, each of R¹, R² and R³ independently indicates a hydrogen atom or an organic group, X indicates a single bond or a bonding chain, and each of R⁴, R⁵ and R⁶ independently indicates a hydrogen atom or an organic group.

[No Figure]